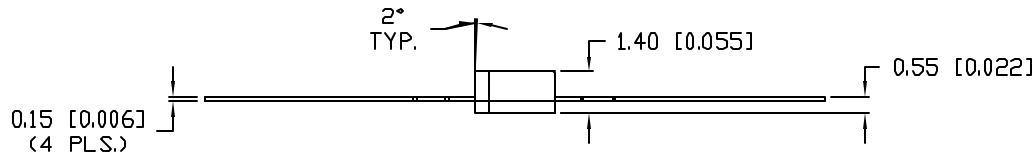
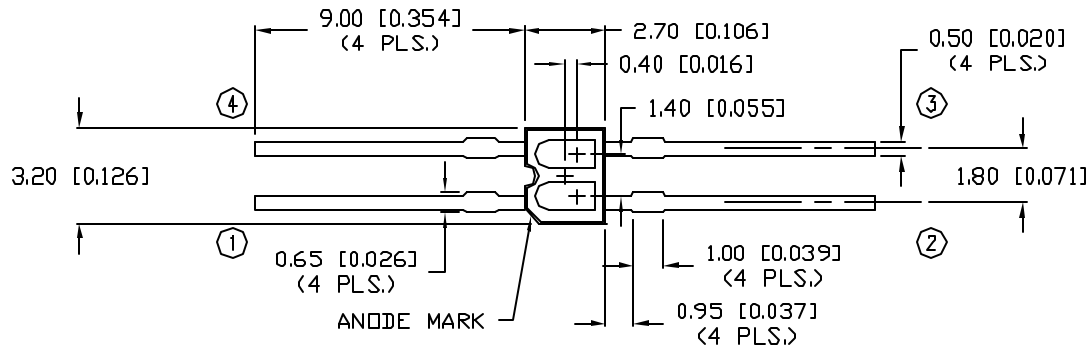
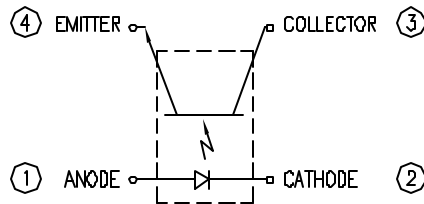


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PART NUMBER		REV.
OED-SR-105		
REV.	E.C.N. NUMBER AND REVISION COMMENTS	DATE



TOP VIEW PINLAYOUT



ELECTRO-OPTICAL CHARACTERISTICS  $T_A=25^\circ\text{C}$

PARAMETER	SYMBOL	MIN	TYP	MAX	UNITS	TEST COND
<b>INPUT:</b>						
FORWARD VOLTAGE	$V_f$			1.3	V	$I_f = 10 \text{ mA}$
REVERSE CURRENT	$I_r$			10	$\mu\text{A}$	$V_r = 5 \text{ V}$
<b>OUTPUT:</b>						
COLLECTOR DARK CURRENT	$I_{ceo}$			0.2	$\mu\text{A}$	$V_{ce} = 10 \text{ V}$
COLLECTOR LIGHT CURRENT	$I_L$	90			$\mu\text{A}$	$V_{ce} = 5 \text{ V}$ $I_f = 10 \text{ mA}$
LEAKAGE CURRENT	$I_{ceod}$			0.2	$\mu\text{A}$	$V_{ce} = 5 \text{ V}$ $I_f = 10 \text{ mA}$
<b>SWITCHING SPEEDS:</b>						
RIISING TIME	$T_r$		30		$\mu\text{s}$	$V_{cc} = 2 \text{ V}$ $I_c = 0.1 \text{ mA}$
FALLING TIME	$T_f$		25		$\mu\text{s}$	$R_l = 1 \text{ K } \Omega$

LIMITS OF SAFE OPERATION AT  $25^\circ\text{C}$

PARAMETER	SYMBOL	MAX	UNITS
<b>INPUT:</b>			
REVERSE VOLTAGE	$V_r$	5	V
POWER DISSIPATION	$P_d$	75	mW
FORWARD CURRENT	$I_f$	50	mA
<b>OUTPUT:</b>			
COLLECTOR POWER DISSIPATION	$P_c$	50	mW
COLLECTOR CURRENT	$I_c$	20	mA
C-E VOLTAGE	$V_{ceo}$	30	V
E-C VOLTAGE	$V_{eco}$	3	V
OPERATING TEMP.	$T_{opr}$	-20 TO +85	$^\circ\text{C}$
STORAGE TEMP.	$T_{stg}$	-30 TO +100	$^\circ\text{C}$
SOLDERING TEMP.	$T_{sol}$	+240	$^\circ\text{C}$
2.0mm FROM BODY	dist.		5 SEC. MAX

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\*UNLESS OTHERWISE SPECIFIED TOLERANCE IS  $\pm 0.25 \text{ mm}$  ( $\pm 0.010$ " )

REV.	PART NUMBER
	OED-SR-105

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290 E. HELLEN ROAD  
 PALATINE, ILLINOIS 60067  
 PHONE: 1-847-359-2790  
 WEB: HTTP://WWW.LUMEX.COM

2.7mm x 3.2mm AXIAL PHOTO REFLECTIVE SENSOR,  
 4 LEADED.

**RELIABILITY NOTE**  
 OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN BY:	CHECKED BY:	APPROVED BY:	DATE: 10-22-99
			PAGE: 1 OF 1
			SCALE: N/A

TM/DJ